A300 FOUPs

Front opening unified pod platform with super microenvironment control

Our A300 FOUP (front opening unified pod) is an environmental wafer isolation pod that provides superior protection from contamination. It is designed for automated or manual handling of 300 mm wafers. Integral wafer supports allow precise wafer plane performance and reliable wafer access. An optional, robust ESD shell provides added wafer protection in applications prone to electrostatic charge accumulation.

We offer 25-capacity FOUPs for standard wafer processing and a 13-capacity format that is optimized for special applications including bonded and thin wafers. All configurations are easy to clean and maintain, provide proven long-term reliability, and are fully SEMI compliant.



A300 FOUPs are available for thin, standard (shown), and thick 300 mm wafers

APPLICATIONS

 Front opening unified pod platform that provides clean and secure 300 mm transport and handling

FEATURES & BENEFITS

25- or 13-capacity designs	Provide versatility in thin, standard, or thick wafer processing applications	
Optimized materials, such as Entegris moisture barrier (EBM)	Provide wafer contact and microenvironment control, enabling leading-edge wafer processing technology	
Optional ESD shell	Offers added wafer protection in environments prone to electrostatic charge accumulation	
Industry-proven door	Provide equipment interoperability and long life	
Integral wafer supports	Allow excellent wafer plane performance and reliable wafer access	
Advanced purge options available	Accommodate process requirements such as maximum gas dispersion or front/rear purge	



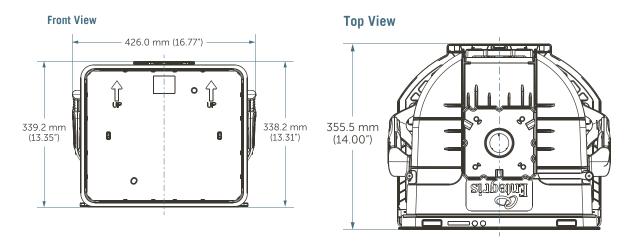
SPECIFICATIONS

		25 Capacity	13 Capacity
Materials of construction	Shell, door housing, door panels	Ultrapure polycarbonate (PC), carbon-filled barrier material	Carbon-filled barrier material
	Wafer supports and contact areas (shell, door housing, door components)	Carbon-filled PC, carbon-filled barrier material	Carbon-filled barrier material
	Door seal	Thermoplastic el	astomer
Dimensions	Width	426 mm (16.8")	
	Depth	355 mm (14.0")	
	Height	338 mm (13.3")	
Weight	Empty	5.4 kg (11.82 lb)	<6 kg (13.23")
	With wafers	8.2 kg (18.18 lb)	Depends on wafer thickness
Wafer spacing		10 mm (0.39")	20 mm (0.78")

Configuration Options

	25 Capacity	13 Capacity
Shell and door colors options	Amber, blue, clear, green, red, black (ESD shell only)	PC clear, EBM black
Purge options	Front/rear standard purge Rear advanced diffuser	Front/rear standard purge
Segregation options	Configurable info pads	Configurable info pads
Identification options	Colored handles - amber, black, blue, green, red, white, yellow Colored cardholders - amber, green, white Bar code and alphanumeric character labels RFID tags with read/write capability	

DIMENSIONS



FOR MORE INFORMATION

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